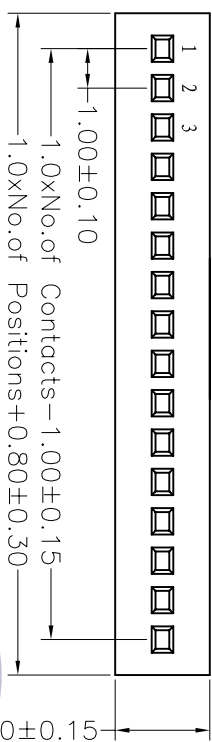


# HSP

NOTES:  
 Current Rating: 1.0AMP  
 Contact Resistance: 20mΩ Max  
 Withstand Voltage: 500V AC/DC  
 Insulation Resistance: 1000MΩ Min  
 Operation Temperature: -40°C to +105°C

Contact Material: Phosphor Bronze  
 Contact plating: Au or Sn over Ni  
 Insulator Material: LCP+30%GF UL94V-0



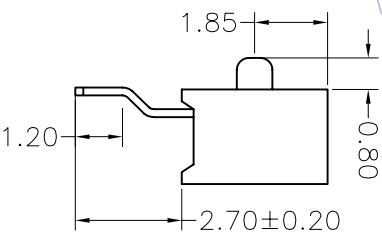
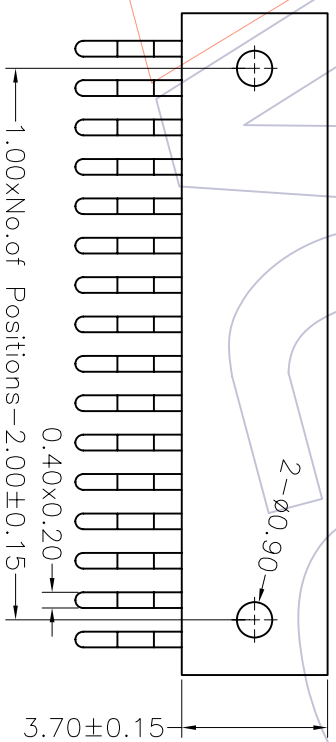
Recommended P.C.B Layout(Top Side)  
 (PCB BOARD TOLERANCE±0.05)

## Ordering Information

2537-1 XX Z XX DUN X 1

No. of Pins per Row: 02-50Pin  
 Contact Plating:  
 G0=Gold Flash  
 G1=5u"Gold  
 G2=5u"Gold  
 G3=10u"Gold  
 G4=15u"Gold  
 G5=30u"Gold  
 S0=Gold Flash/Tin  
 S1=3u"Gold/Tin  
 S2=5u"Gold/Tin  
 S3=10u"Gold/Tin  
 S4=15u"Gold/Tin  
 S5=30u"Gold/Tin  
 SN=Tin

Packing:  
 T=Tube  
 R=Tape&Reel



REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	OPERATION	DRAW	WEIXD	08.09.23	SCALE	5:1	 <b>WCON</b> 维峰五金电子有限公司 WAFER HARDWARE ELECTRONICS CO.,LTD	PART NO.	2537-1XXXDUNX1
A0	08/09/23	NEW			XXX	DESIGN		UNIT	mm	A4		TITLE:	FH1.00 SINGLE ROW 90° SMT H=3.7
					XXX	CHECK		SIZE	1/1		PROJ.	Customer NO.	
					Angle	APPROVE							
					± .3'								
					DIM								
					TOL								